

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 245 | (machine or apparatus or tool or device).ti and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/13 13:36 |
| L2 | 312 | (machine or apparatus or tool or device).ab. and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/13 13:39 |
| L3 | 130 | 2 not 1 | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/13 13:36 |
| L4 | 6463 | (machine or apparatus or tool or device).ab. and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/13 13:39 |

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|----|------|---|--|----|----|---------------------|
| L5 | 5778 | (machine or apparatus or tool or device).ti. and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:39 |
| L6 | 7198 | (machine or apparatus or tool or device or system).ti. and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:40 |
| L7 | 145 | 6 and ((solder or bump) and ball) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:40 |
| L8 | 139 | 7. not 2 | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:43 |
| L9 | 242 | 6 and ball and (wafer or semiconductor) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:43 |

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| L10 | 168 | 9 not 7 | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:43 |
| L18 | 20306 | (bump and ball and form\$3) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:52 |
| L19 | 407 | (bump and ball and form\$3). ti. | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:53 |
| L20 | 41 | (hidaka near masao).in. | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:53 |
| S1 | 3685 | ((29/592.1) or (29/825) or (29/407.01) or (29/407.09) or (29/407.1) or (29/525.13) or (29/559)).CCLS. | US-PGPU B; USPAT; USOCR | OR | OFF | 2005/06/12 22:36 |
| S2 | 3907 | ((29/464) or (29/466) or (29/468) or (29/709) or (29/714) or (29/721) or (29/759) or (29/760)).CCLS | US-PGPU B; USPAT; USOCR | OR | OFF | 2005/06/13 09:39 |

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| S4 | 3583 | S2 not S1 | US-PGPU B; USPAT; USOCR | OR | ON | 2005/06/12 19:52 |
| S5 | 898 | ((29/281.1) or (29/281.4)). CCLS. | US-PGPU B; USPAT; USOCR | OR | OFF | 2005/06/12 22:04 |
| S6 | 528 | ((29/464) or (29/466) or (29/468) or (29/709) or (29/714) or (29/721) or (29/759) or (29/760) or (29/281.1) or (29/281.4)). CCLS. | EPO; JPO; DERWEN T; IBM_TDB | OR | OFF | 2005/06/12 22:15 |
| S7 | 90 | ((29/407.01) or (29/407.09) or (29/407.1) or (29/525.13) or (29/559)).CCLS. | EPO; JPO; DERWEN T; IBM_TDB | OR | OFF | 2005/06/12 22:41 |
| S8 | 1763 | ((29/592.1) or (29/825)). CCLS. | EPO; JPO; DERWEN T; IBM_TDB | OR | OFF | 2005/06/12 22:41 |
| S9 | 0 | S8 and (bump near ball near crimp\$3) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/12 22:42 |
| S10 | 0 | S8 and (bump same ball same crimp\$3) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/12 22:42 |
| S11 | 0 | S8 and (bump and ball and crimp\$3 and (device or apparatus or machine)) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/12 22:56 |
| S12 | 0 | S8 and (ball and crimp\$3 and (device or apparatus or machine)) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/12 22:56 |

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| S13 | 0 | S8 and (bump and ball and crimp\$3) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/12 22:57 |
| S14 | 1 | S8 and (bump and ball) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/12 23:03 |
| S15 | 2836 | ((269/54.4) or (269/54.5) or (269/55) or (269/58) or (269/59) or (269/289R) or (269/909)).CCLS. | US-PGPU B; USPAT; USOCR | OR | OFF | 2005/06/12 23:04 |
| S16 | 2 | (bump adj ball adj crimp\$3 adj (apparatus or machine or device or tool)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:43 |
| S17 | 2 | (bump near ball near crimp\$3 near (apparatus or machine or device or tool)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:43 |
| S18 | 10 | (bump with ball with crimp\$3 with (apparatus or machine or device or tool)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:45 |

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| S19 | 23 | (bump same ball same crimp\$3 same (apparatus or machine or device or tool)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:47 |
| S20 | 13 | S19-not S18 | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:46 |
| S21 | 5147 | (bump same ball same (apparatus or machine or device or tool)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:47 |
| S22 | 2409 | (bump with ball with (apparatus or machine or device or tool)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:48 |
| S23 | 562 | (bump with ball with (apparatus or machine or device or tool)).ab. | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:48 |

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| S24 | 59 | S23 and wafer.ab. | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:55 |
| S25 | 58 | S24 not S19 | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:48 |
| S26 | 95 | S23 and wafer | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:55 |
| S27 | 37 | S26 not S25 | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 09:58 |
| S28 | 2 | S23 and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 13:29 |

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| S29 | 2 | S23 and (align\$4 with (plate or tool or surface)) and ((sample or crimp\$3) with (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:01 |
| S30 | 2 | S23 and (align\$4 same (plate or tool or surface)) and ((sample or crimp\$3) same (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:01 |
| S31 | 2 | S23 and (align\$4 and (plate or tool or surface)) and ((sample or crimp\$3) and (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:02 |
| S32 | 138 | S21 and (align\$4 and (plate or tool or surface)) and ((sample or crimp\$3) and (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:02 |
| S33 | 137 | S32 not S26 | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:10 |

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| S35 | 4 | (Yukihiko near Isa).in. | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:11 |
| S36 | 89 | (UMC near Japan).as | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:19 |
| S37 | 34 | ((crimp\$3 or bond\$3) near (device or mechanism or tool)) and (align\$4 near (plate or tool or surface)) and ((sample or crimp\$3) near (table or surface or plate)) | US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 10:22 |
| S38 | 1905 | ((228/41) or (228/246) or (228/180.22)).CCLS | US-PGPU B; USPAT; USOCR | OR | OFF | 2005/06/13 10:59 |
| S39 | 237 | ((228/41) or (228/246) or (228/180.22)).CCLS. | EPO; JPO; DERWEN T; IBM_TDB | OR | OFF | 2005/06/13 11:19 |
| S40 | 1565 | (29/840).CCLS | US-PGPU B; USPAT; USOCR | OR | OFF | 2005/06/13 11:43 |
| S41 | 703 | (29/840).CCLS. | EPO; JPO; DERWEN T; IBM_TDB | OR | OFF | 2005/06/13 11:43 |

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| S42 | 0 | S41 and (bump near ball) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 11:44 |
| S43 | 0 | S41 and ((bond\$3 or bump) with ball) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 11:44 |
| S44 | 4 | S41 and ((bond\$3 or bump) and ball) | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 11:45 |
| S45 | 26 | S41 and ball | EPO; JPO; DERWEN T; IBM_TDB | OR | ON | 2005/06/13 11:45 |